L Number	Hits	Search Text	DB	Time stamp
-	4	6214193.pn. 6099702.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 11:32
-	2	3950184.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 11:58
-	14	3950184.URPN.	USPAT	2003/04/25 11:58
-	5	("3141793" | "3656173" | "3950184" | "4451507" | "5084483").PN.	USPAT	2003/04/25 12:01
-	17	("3798056" | "3950184" | "4339319" | "4373988" | "4466864" | "4856456" | "5000827" | "5169408" | "5312487" | "5340437" | "5472592" | "5670034" | "5677000" | "5893966" | "5930549" | "6077412" | "6099702").PN.	USPAT	2003/04/25 13:58
-	33	5000827.URPN.	USPAT	2003/04/25 12:04
-	53	5169408.URPN.	USPAT	2003/04/25 12:41
-	33	5000827.URPN.	USPAT	2003/04/25 12:50
-	2247	204/212,225,237,275.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 13:58
-	773	204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 13:58
-	2837	204/212,225,237,275.1.ccls. 204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:00
-	2190	118/416,500,501.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:01
-	5015	(204/212,225,237,275.1.ccls. 204/224r.ccls.) 118/416,500,501.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:01
-	1027	((204/212,225,237,275.1.ccls. 204/224r.ccls.) 118/416,500,501.ccls.) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:02
-	557	(((204/212,225,237,275.1.ccls. 204/224r.ccls.) 118/416,500,501.ccls.) and (semiconductor or wafer)) and (spinning or spin or spun or rotate or rotated or rotating)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:02

-	90	((((204/212,225,237,275.1.ccls. 204/224r.ccls.) 118/416,500,501.ccls.) and (semiconductor or wafer)) and (spinning or spin or spun or rotate or rotated or rotating)) and (recycle or recycling or recylcer or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:36
-	3	("5922138" | "6168691" | "6187152").PN.	USPAT	2003/04/25 14:29
-	0	6352623.URPN.	USPAT	2003/04/25 14:33
-	3776	205/122,123,157,220.ccls. 427/98,299,352.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:34
-	940	(205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:34
-	504	((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:35
-	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)) and (recycle or recycling or recylcer or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:36
-	90	((((204/212,225,237,275.1.ccls. 204/224r.ccls.) 118/416,500,501.ccls.) and (semiconductor or wafer)) and (spinning or spin or spun or rotate or rotated or rotating)) and (recycle or recycling or recycler or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 15:01
-	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)) and (recycle or recycling or recycler or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:37
-	225	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)) and (spin or spinning or spun or rotate or rotating or rotated or revolve or revolved or revolving)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:37

-		40	(((((205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)) and (cleaning or clean or cleaned or rinsed or rinse or rinsing or wash or washing or washed)) and (spin or spinning or spun or rotate or rotating or rotated or revolve or revolved or revolving)) and (recycle or recycling or recycler or reclaim or reclamation or recycled or reclaimed or recover or recovered or recovery or recovering)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:37
-		11	(US-6099702-$ or US-6214193-$ or US-5677000-$ or US-3950184-$ or US-6551487-$ or US-6299751-$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/10 11:50
-		1	2000wo-us28210.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/10 11:53
-		16	6099702.URPN.	USPAT	2003/06/10 11:51
-		15	("3798056" | "3950184" | "4339319" | "4373988" | "4466864" | "4856456" | "5000827" | "5169408" | "5312487" | "5340437" | "5472592" | "5670034" | "5677000" | "5893966" | "5930549").PN.	USPAT	2003/06/10 11:51
-		0	6214193.URPN.	USPAT	2003/06/10 11:51
-		17	("3798056" | "3950184" | "4339319" | "4373988" | "4466864" | "4856456" | "5000827" | "5169408" | "5312487" | "5340437" | "5472592" | "5670034" | "5677000" | "5893966" | "5930549" | "6077412" | "6099702").PN.	USPAT	2003/06/10 11:51
-		33	6099702.URPN. (("3798056" | "3950184" | "4339319" | "4373988" | "4466864" | "4856456" | "5000827" | "5169408" | "5312487" | "5340437" | "5472592" | "5670034" | "5677000" | "5893966" | "5930549").PN.) 6214193.URPN. (("3798056" | "3950184" | "4339319" | "4373988" | "4466864" | "4856456" | "5000827" | "5169408" | "5312487" | "5340437" | "5472592" | "5670034" | "5677000" | "5893966" | "5930549" | "6077412" | "6099702").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/10 11:51
-		1	2001-580725.NRAN.	DERWENT	2003/06/10 11:52
-		12	(("6139703") or ("6080291") or ("5932077") or ("5447615") or ("5421987") or ("5344491")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:29
-		1	836844.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:47
-		2401	204/199,212,232,263,275.1,297.01,297.06,297.07,297.08.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:48

-	780	204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:48
-	3033	204/199,212,232,263,275.1,297.01,297.06,297.07,297.08 RPAT; 204/224r.ccls.	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:48
-	73	(204/199,212,232,263,275.1,297.01,297.06,297.07,297.08PAT; 204/224r.ccls.) and ((multiple or plural$3 or second) near (outlet or withdraw$3 or collect$4))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:49
-	26	(204/199,212,232,263,275.1,297.01,297.06,297.07,297.08PAT; 204/224r.ccls.) and ((multiple or plural$3) near (outlet or withdraw$3 or collect$4))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:49
-	47	((204/199,212,232,263,275.1,297.01,297.06,297.07,297.08PATs. 204/224r.ccls.) and ((multiple or plural$3 or second) near (outlet or withdraw$3 or collect$4))) not ((204/199,212,232,263,275.1,297.01,297.06,297.07,297.08RWENT; 204/224r.ccls.) and ((multiple or plural$3) near (outlet or withdraw$3 or collect$4)))	US-PGPUB; EPO; JPO; IBM_TDB	2003/06/10 12:52
-	16	(204/199,212,232,263,275.1,297.01,297.06,297.07,297.08PAT; 204/224r.ccls.) and (situ near (rins$3 or process$3 or clean$3 or wash$3))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 12:56
-	2	5932077.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 14:58
-	25	5932077.URPN.	USPAT	2004/01/07 14:58
-	64	204/198,199.ccls. and (microelectronic or wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 15:12
-	18	204/198,199.ccls. and (microelectronic or wafer or semiconductor) and (spray$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 15:12
-	2342	204/212,225,237,275.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 09:18

-	811	204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 09:18
-	2957	204/212,225,237,275.1.ccls. 204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 09:18
-	373	(204/212,225,237,275.1.ccls. 204/224r.ccls.) and (wafer or semiconductor or microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 09:19
-	8	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and (wafer or semiconductor or microelectronic)) and (tilt$5 and spray$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 09:19
-	14	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and (wafer or semiconductor or microelectronic)) and (tilt$5 and (spray$5 or nozzle))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 10:12
-	100	(204/198-227.ccls. and (microelectronic or wafer or semiconductor)) and ((contact or electrode or cathode) with (clean$3 or wash$3 or rins$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 11:48
-	2	6156167.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/08 11:48
-	1	836844.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 09:24
-	438	204/198-227.ccls. and (microelectronic or wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/09 09:53
-	20	(204/198-227.ccls. and (microelectronic or wafer or semiconductor)) and (tilt$4 with (wafer or substrate or semiconductor or microelectronic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/09 09:53
-	5	6613214.pn. 6258220.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/09 09:44
-	3	6251236.pn. 6258220.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/09 09:44
-	11422	(205/$.ccls. or 204/$.ccls.) and (microelectronic or wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/09 09:53

-	121	((205/$.ccls. or 204/$.ccls.) and (microelectronic or wafer or semiconductor)) and (tilt$4 with (wafer or substrate or semiconductor or microelectronic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/09 09:54
-	101	(((205/$.ccls. or 204/$.ccls.) and (microelectronic or wafer or semiconductor)) and (tilt$4 with (wafer or substrate or semiconductor or microelectronic))) not ((204/198-227.ccls. and (microelectronic or wafer or semiconductor)) and (tilt$4 with (wafer or substrate or semiconductor or microelectronic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/09 09:54
-	1554	422/292,300.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:54
-	16	422/292,300.ccls. and (wafer or microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:54
-	21646	(clean$3 or rins$3) near3 (wafer or microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:55
-	21418	(clean$3 or rins$3) near3 (wafer or microelectro((clean$3 or rins$3) near3 (wafer or microelectronic)) and (spray or stream)nic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:55
-	4282	((clean$3 or rins$3) near3 (wafer or microelectronic)) and (spray or stream)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:55
-	3472	(((clean$3 or rins$3) near3 (wafer or microelectronic)) and (spray or stream)) and (chemical or fluid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:55
-	2269	((((clean$3 or rins$3) near3 (wafer or microelectronic)) and (spray or stream)) and (chemical or fluid)) and (chamber or container)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:56
-	4644	134/$.ccls. and (wafer or microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:56

-	452	134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and (wafer or microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:56
-	320	(134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and (wafer or microelectronic)) and (clean$3 or rins$3) near3 (wafer or microelectronic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:56
-	196	((134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and (wafer or microelectronic)) and (clean$3 or rins$3) near3 (wafer or microelectronic)) and (spray or stream)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:57
-	132	(((((134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and (wafer or microelectronic)) and (clean$3 or rins$3) near3 (wafer or microelectronic)) and (spray or stream)) and (chemical or fluid)) and (chamber or container)) and (rais$3 or lower$3 or vertical$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:57
-	2	6050275.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 10:57